



High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

VSMY2853RG

VSMY2853G



22689

DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2853 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR illumination
- 3D TV

FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- Peak wavelength: $\lambda_p = 850$ nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: $\phi = \pm 28^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2503X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMY2853RG	35	± 28	850	10
VSMY2853G	35	± 28	850	10

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2853RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2853G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	t _p /T = 0.5, t _p = 100 μs	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	A
Power dissipation		P _V	190	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	acc. figure 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W

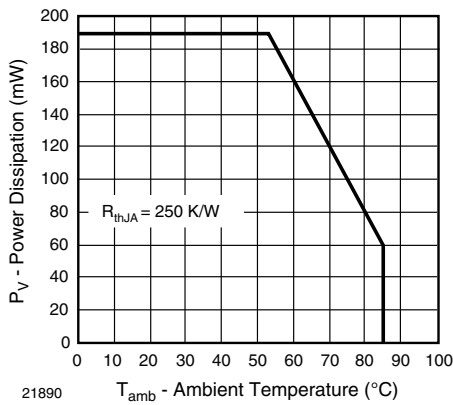


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

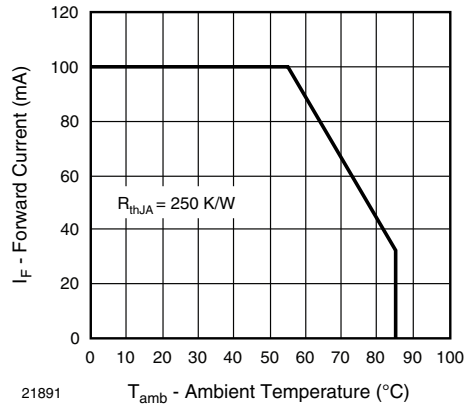


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F		1.65	1.9	V
	I _F = 1 A, t _p = 100 μs	V _F		2.9		V
Temperature coefficient of V _F	I _F = 1 mA	TK _{V_F}		-1.45		mV/K
	I _F = 10 mA	TK _{V_F}		-1.3		mV/K
Reverse current		I _R	not designed for reverse operation			μA
Junction capacitance	V _R = 0 V, f = 1 MHz, E = 0 mW/cm ²	C _J		125		pF
Radiant intensity	I _F = 100 mA, t _p = 20 ms	I _e	20	35	50	mW/sr
	I _F = 1 A, t _p = 100 μs	I _e		300		mW/sr
Radiant power	I _F = 100 mA, t _p = 20 ms	φ _e		55		mW
Temperature coefficient of radiant power	I _F = 100 mA	TKφ _e		-0.35		%/K
Angle of half intensity		φ		± 28		deg
Peak wavelength	I _F = 100 mA	λ _p	840	850	870	nm
Spectral bandwidth	I _F = 30 mA	Δλ		30		nm
Temperature coefficient of λ _p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		10		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		10		ns

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

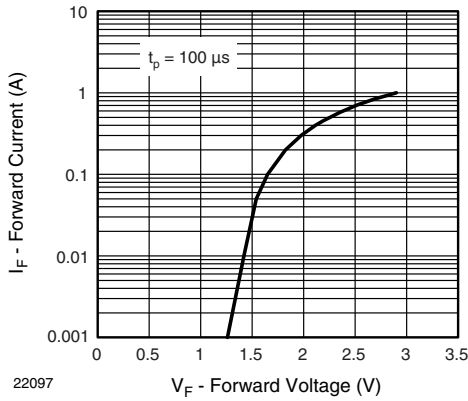


Fig. 3 - Forward Current vs. Forward Voltage

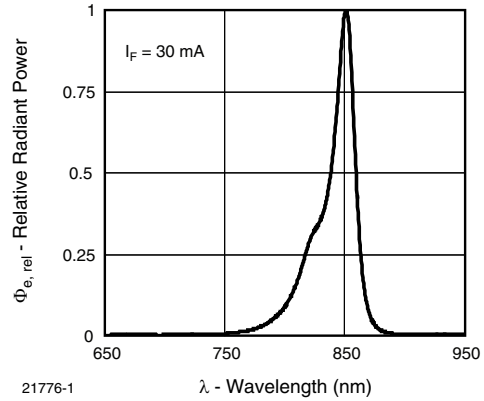


Fig. 5 - Relative Radiant Power vs. Wavelength

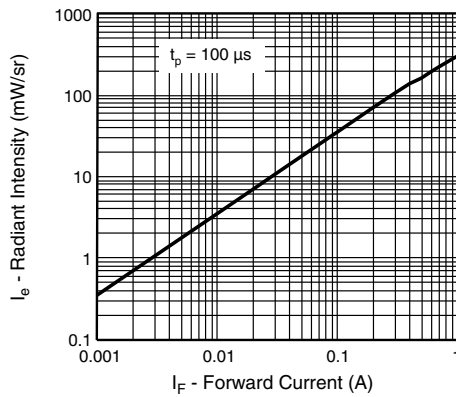


Fig. 4 - Radiant Intensity vs. Forward Current

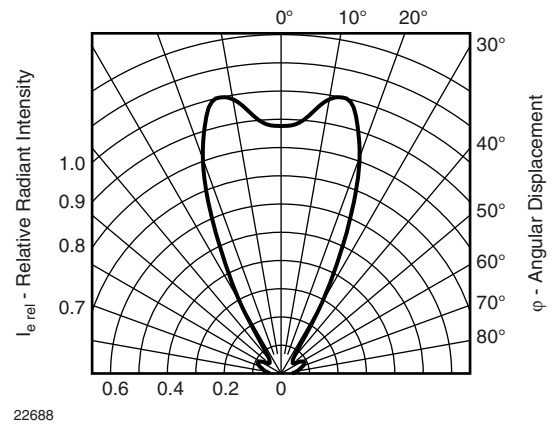


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

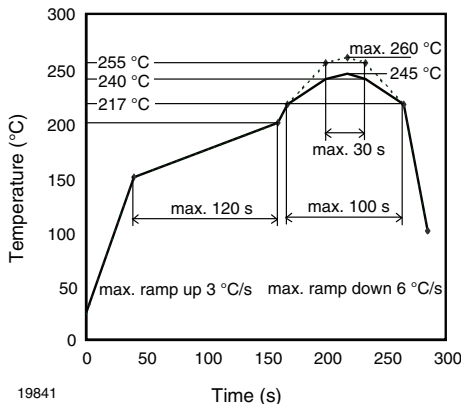


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

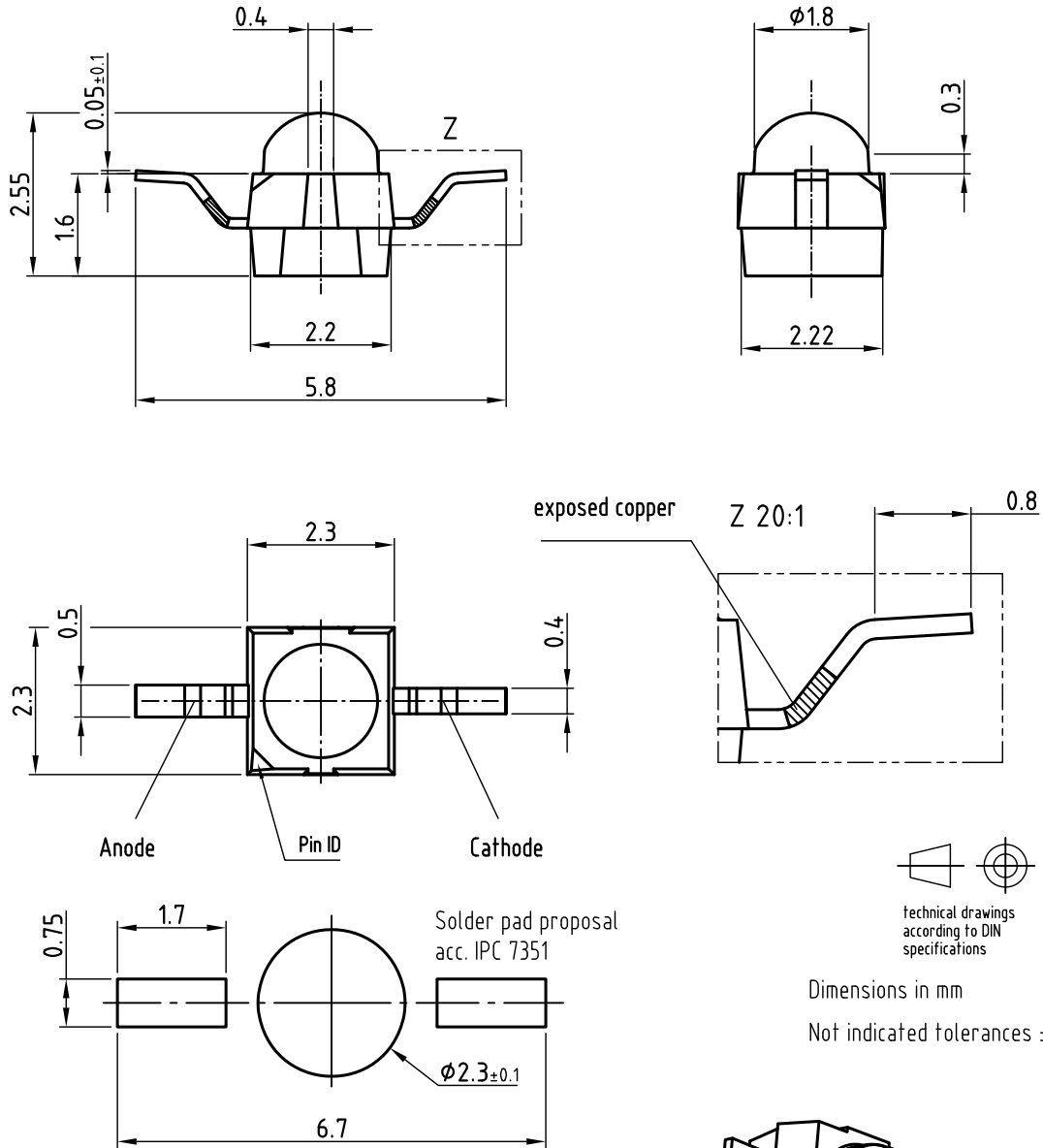
Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 °C), RH < 5 %.

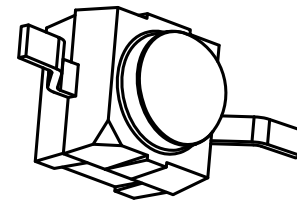


PACKAGE DIMENSIONS in millimeters: VSMY2853RG



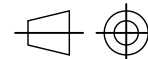
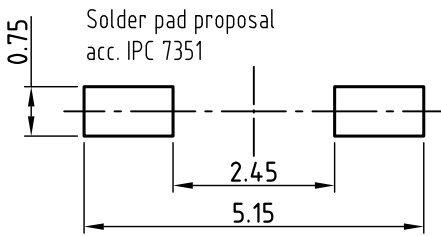
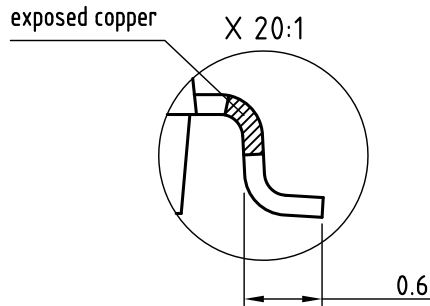
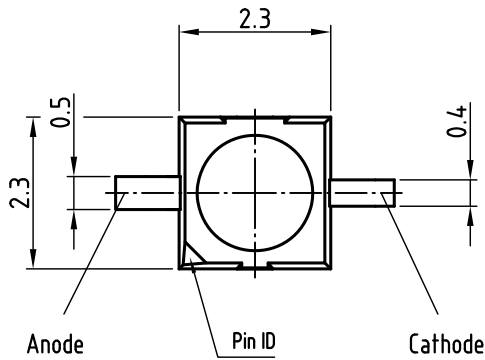
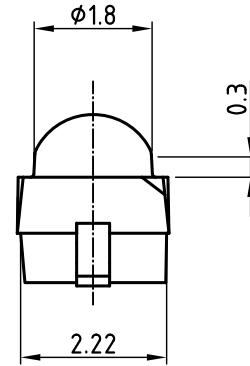
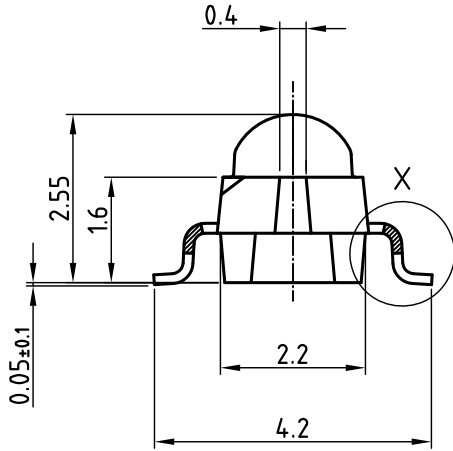
Drawing refers to following types: VSMY2853RG

Drawing-No.: 6.544-5409.03-4
Issue: prel. 03.08.12





PACKAGE DIMENSIONS in millimeters: VSMY2853G



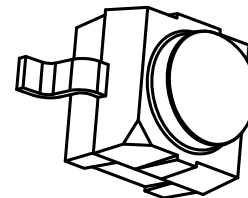
technical drawings according to DIN specifications

Dimensions in mm

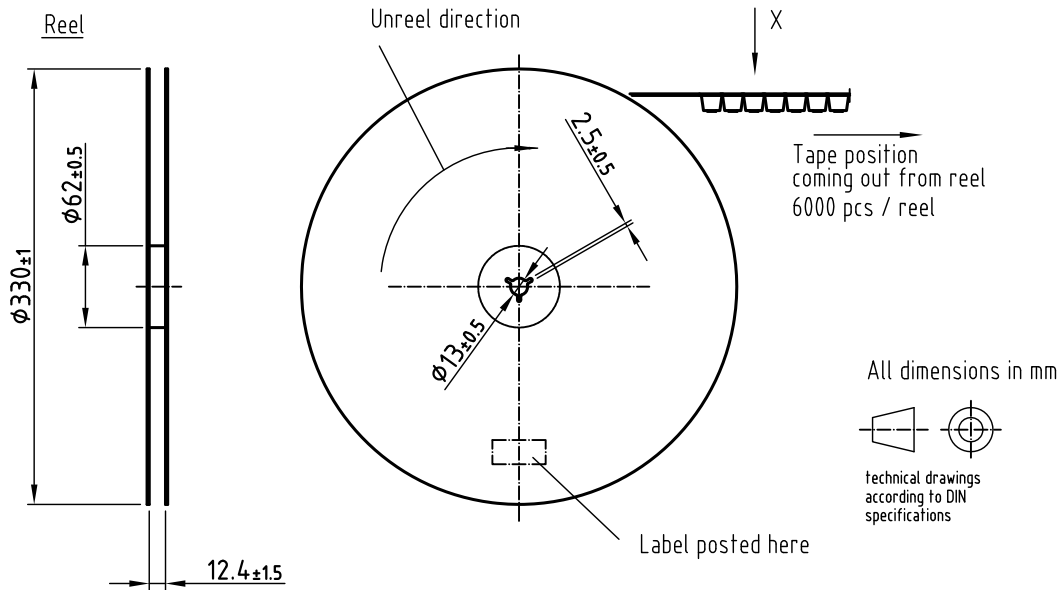
Not indicated tolerances ±0.2

Drawing refers to following types: VSMY2853G

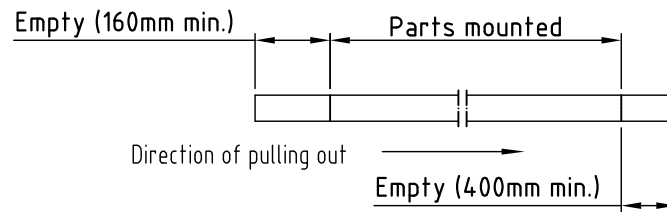
Drawing-No.: 6.544-5408.03-4
Issue: prel; 03.08.12



TAPING AND REEL DIMENSIONS in millimeters: VSMY2853RG

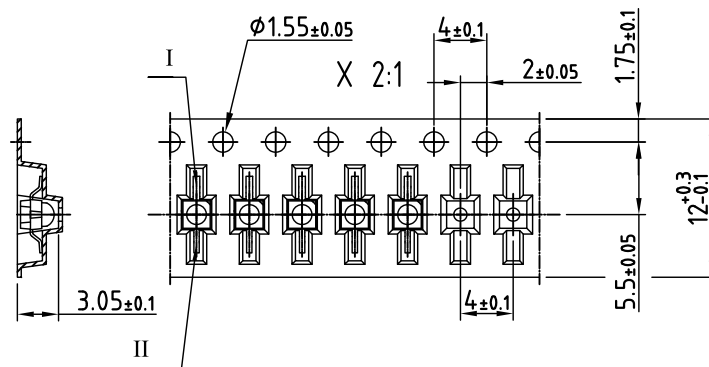


Leader and trailer tape:



Terminal position in tape

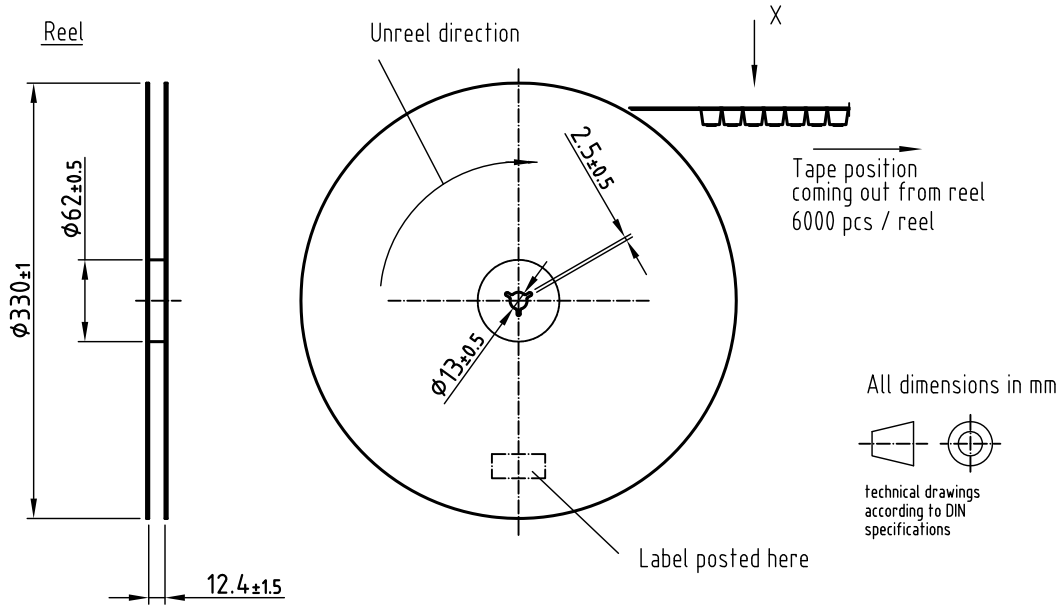
Device	Lead I	Lead II
V SMB2943RGX01	Cathode	Anode
V SMF2893RGX01		
V EMD2x03X01		
V EMT2x03X01	Collector	Emitter
V SMY2853RG	Anode	Cathode



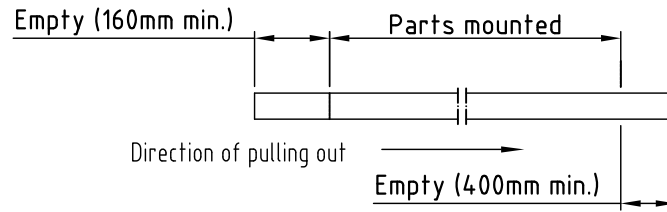
Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5100.02-4
Issue: prel; 03.08.12

TAPING AND REEL DIMENSIONS in millimeters: **VSMY2853G**

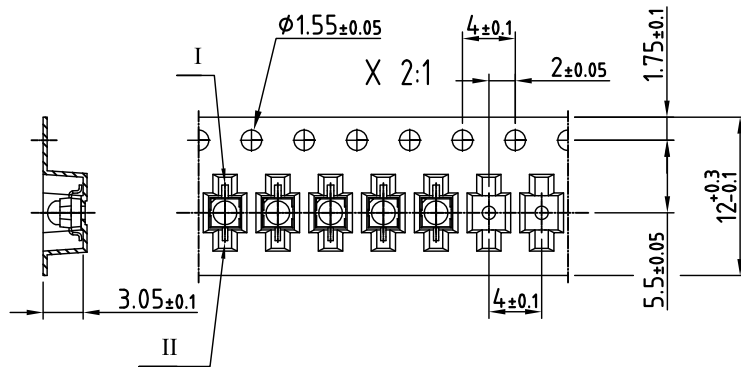


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VSMB2943GX01	Cathode	Anode
VSMF2893GX01		
VEMD2x23X01		
VEMT2x23X01	Collector	Emitter
VSMY2853G	Anode	Cathode



Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5091.21-4
Issue: prel; 03.08.12



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.